



Electronics Packages

Electronics software offers three core packages:

/ Ansys Electronics Enterprise

Premier software package for the engineer solving problems across the electronics design spectrum. All Ansys electronics technologies are included in this single user package.

/ Ansys Electronics Pro 2D

Electronics Pro 2D is ideal for 2D low frequency electromagnetic analysis, 2D parameter extraction and RF system analysis for the prediction of radio frequency interference and circuit simulation with advanced RF functionality.

/ Ansys Electronics Premium

Premium features of our flagship products.

Ansys HFSS

Ansys Maxwell

| Electronics Premium HFSS | Electronics Premium Maxwell | | | |
|--|---|--|--|--|
| All HFSS 3D solvers | 3D low frequency static and transient solvers | | | |
| ECAD and MCAD modeling and translation | ECAD and MCAD modeling and translation | | | |
| Advanced circuit analysis | Advanced circuit analysis | | | |
| Electronics Pro 2D | Electronics Pro 2D | | | |

Ansys Icepak

Ansys Slwave

| Electronics Premium Icepak | Electronics Premium SIwave |
|--|--|
| All Icepak solvers | Slwave DC and Power Integrity Solvers |
| Mechanical thermal and modal solvers | ECAD and MCAD modeling and translation |
| ECAD and MCAD modeling and translation | Advanced circuit analysis |
| Advanced circuit analysis | Electronics Pro 2D |
| Electronics Pro 2D | |

/ Electronics Enterprise

Electronics Enterprise is a comprehensive single user software package that includes all the capabilities of Electronics Pro 2D and Electronics Premium and enables many additional advanced capabilities. This powerful software package enables engineers to analyze a broad range of electromagnetic, electromechanical, RF, circuit and system-level applications with access to the full suite of Ansys Electronics simulation tools, including coupled multiphysics solutions (e.g. HFSS and Icepak electrothermal simulations).

/ Electronics Pro 2D

Electronics Pro 2D software package enables engineers to perform 2D electromagnetic and 2D electromechanical circuit and system analysis. It includes 2D quasi-static, transient and RLGC extraction capabilities. An intuitive template-based design flow gives you the ability to automatically generate and analyze different electric machine designs and electronic transformers.

In addition, the Electronics Pro 2D software package provides analog, digital and system-level circuit analysis tools as well as radio-frequency interference (RFI) and electromagnetic interference (EMI) solutions.





ELECTRONICS

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The complete list of the Electronics Product Package contents is available in the table below.

| | | Electronies | | Electric micro | Electronies | | Flori i | | |
|--|-----------------------|--|--------------------------------|-----------------------------------|-------------------------------|----------------------------------|----------------------------------|---------------------------|-------------------------------------|
| Electronics PPE Capabilities | Electronics Pro 2D | Electronics Enterprise Prep/Post | Electronics Premium HFSS | Electronics Premium Maxwell | Electronics Premium Q3D | Electronics Premium Icepak | Electronics Premium Slwave | Electronics Enterprise | Electronics Enterprise Solver |
| Electronics Desktop Prep/Post: UI for Circuit and 2D Solvers | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | |
| Maxwell 2D (Quasistatic, Transient, PExprt, RMxprt) | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | |
| 2D Extractor (Transmission line simulations) | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | |
| Optimetrics, Four (4) HPC cores | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | |
| LF (aka Simplorer) Analog & Digital Circuit | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | |
| HF Circuit: Includes DC, Transient, RF Circuit, IBIS, PSPICE, Verilog A, HSPICE | ✓ | ✓ | ✓ | ✓ | ✓ | ~ | ~ | ✓ | |
| ЕМІТ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | |
| Network Data Explorer | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | |
| Electronics Enterprise Prep/Post: UI for SIwave and 3D Solvers | | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | |
| ECAD & MCAD Translation | | | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ | ✓ |
| HFSS Solve; Including Transient, IE, PO, and SBR+ (ADP not included*) | | | / * | | | | | ✓ | ✓ |
| Maxwell 3D Solve | | | | ✓ | | | | ✓ | ✓ |
| Q3D Extractor Solve | | | | | ✓ | | | ✓ | ✓ |
| Icepak Solve | | | | | | ✓ | | ✓ | ✓ |
| SIwave DC, Resonance, AC, PSI, CPA-FEM & Q3D, PI Advisor | | | | | | | / * | ✓ | ✓ |
| SIwave HFSS Regions √*(w Electronics Enterprise or Prem. HFSS + Prem. SIwave | | | | | | | | / * | ✓ |
| Slwave SNA, Near/Far Field, Electromigration, Zo, Cross talk, EMS, EMI Scan, TDR/SI Wiz. | | | | | | | | ✓ | ✓ |
| Nexxim IBIS-AMI/QE/VE | | | | | | | | ✓ | ✓ |
| Design of Experiments | | | | | | | | ✓ | ✓ |
| SpaceClaim Direct Modeler | | | | | | | | ✓ | ✓ |
| *Accelerated Doppler Processing (ADP) for SBR+ | | | | | | | | ✓ | ✓ |